

ABSTRACT OF THE DISCLOSURE

The present invention is directed to a structure of a surface mounted resettable over-current protection device and a method for manufacturing the same. First, a raw material substrate having two ends is provided. On each of the two ends of the raw material substrate, a patterned conducting metal foil is formed. Then, the raw material substrate is cut to form a grid-shaped substrate having a plurality of strip-shaped structural parts. An insulating layer is formed to enclose the whole grid-shaped substrate, allowing parts of the patterned metal foil layers on the ends of the strip-shaped structural parts to be exposed. Next, the strip-shaped structural parts of the grid-shaped substrate are cut into a plurality of chips, each chip having two cut sections. Finally, two terminal electrodes are formed on the both cut sections of each chip.